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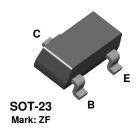




# 2N4126

# **MMBT4126**





# **PNP General Purpose Amplifier**

This device is designed for general purpose amplifier and switching applications at collector currents to 10 µA as a switch and to 100 mA as an amplifier.

#### **Absolute Maximum Ratings\*** TA = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>CEO</sub>	Collector-Emitter Voltage	25	V
V <sub>CBO</sub>	Collector-Base Voltage	25	V
V <sub>EBO</sub>	Emitter-Base Voltage	4.0	V
I <sub>C</sub>	Collector Current - Continuous	200	mA
T <sub>J</sub> , T <sub>stg</sub>	Operating and Storage Junction Temperature Range	-55 to +150	°C

<sup>\*</sup>These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

- 1) These ratings are based on a maximum junction temperature of 150 degrees C.
  2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.
- 3) All voltages (V) and currents (A) are negative polarity for PNP transistors.

#### **Thermal Characteristics** TA= 25°C unless otherwise noted

Symbol	Characteristic	M	Units	
		2N4126	*MMBT4126	
$P_D$	Total Device Dissipation	625	350	mW
	Derate above 25°C	5.0	2.8	mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case	83.3		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	200	357	°C/W

<sup>\*</sup>Device mounted on FR-4 PCB 1.6" X 1.6" X 0.06."

# PNP General Purpose Amplifier (continued)

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TA = 25°C unless otherwise noted

Symbol	Parameter	Parameter Test Conditions Mir			
OFF CHAI	RACTERISTICS				
$V_{(BR)CEO}$	Collector-Emitter Breakdown Voltage	$I_C = 1.0 \text{ mA}, I_B = 0$	25		V
V <sub>(BR)CBO</sub>	Collector-Base Breakdown Voltage	$I_C = 10 \mu A, I_E = 0$	25		V
V <sub>(BR)EBO</sub>	Emitter-Base Breakdown Voltage	$I_{C} = 10 \ \mu\text{A}, \ I_{C} = 0$	4.0		V
I <sub>CBO</sub>	Collector Cutoff Current	$V_{CB} = 20 \text{ V}, I_{E} = 0$		50	nA
I <sub>EBO</sub>	Emitter Cutoff Current	$V_{EB} = 3.0 \text{ V}, I_{C} = 0$		50	nA

#### ON CHARACTERISTICS\*

h <sub>FE</sub>	DC Current Gain	$I_C = 2.0 \text{ mA}, V_{CE} = 1.0 \text{ V}$	120	360	
		$I_C = 50 \text{ mA}, V_{CE} = 1.0 \text{ V}$	60		
V <sub>CE(sat)</sub>	Collector-Emitter Saturation Voltage	$I_C = 50 \text{ mA}, I_B = 5.0 \text{ mA}$		0.4	V
V <sub>BE(sat)</sub>	Base-Emitter Saturation Voltage	$I_C = 50 \text{ mA}, I_B = 5.0 \text{ mA}$		0.95	V

#### SMALL SIGNAL CHARACTERISTICS

f <sub>T</sub>	Current Gain - Bandwidth Product	$I_C = 10 \text{ mA}, V_{CE} = 20 \text{ V},$ f = 100  MHz	250		MHz
C <sub>ibo</sub>	Input Capacitance	$V_{EB} = 0.5 \text{ V}, I_{C} = 0,$ f = 1.0 MHz		10	pF
C <sub>cb</sub>	Collector-Base Capcitance	$V_{CB} = 5.0 \text{ V}, I_{E} = 0,$ f = 100 kHz		4.5	pF
h <sub>fe</sub>	Small-Signal Current Gain	$I_C = 2.0 \text{ mA}, V_{CE} = 10 \text{ V},$ f = 1.0  kHz	120	480	
NF	Noise Figure	$I_{C} = 100 \ \mu\text{A}, \ V_{CE} = 5.0 \ V, \ R_{S} = 1.0 \ k\Omega, \ f = 10 \ Hz \ to \ 15.7 \ kHz$		4.0	dB

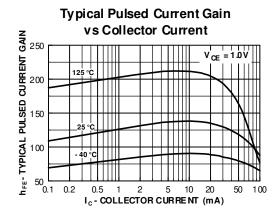
<sup>\*</sup>Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle  $\leq$  2.0%

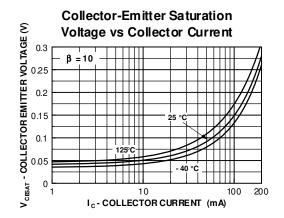
 $\textbf{NOTE:} \ \textbf{All voltages (V) and currents (A) are negative polarity for PNP transistors.}$ 

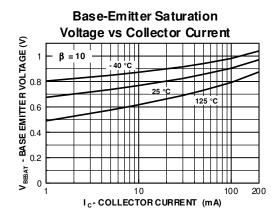
# **PNP General Purpose Amplifier**

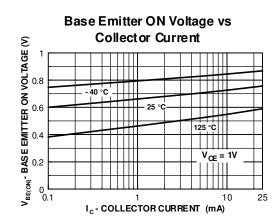
(continued)

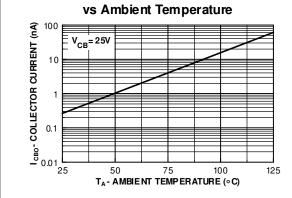
# **Typical Characteristics**



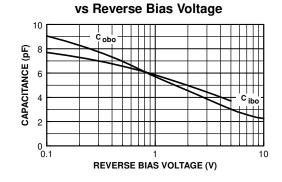








**Collector-Cutoff Current** 



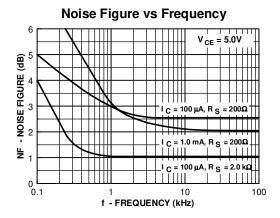
**Common-Base Open Circuit** 

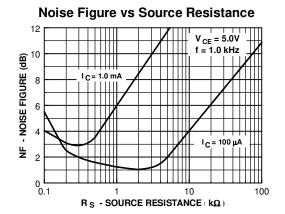
**Input and Output Capacitance** 

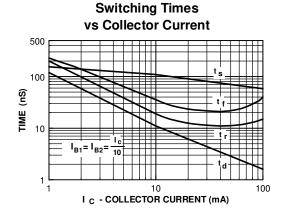
# **PNP General Purpose Amplifier**

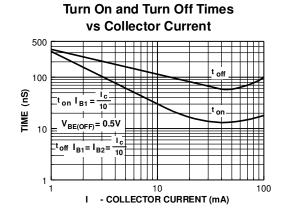
(continued)

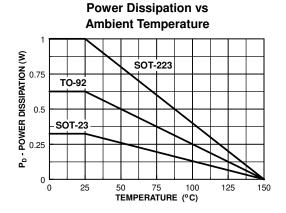
# Typical Characteristics (continued)







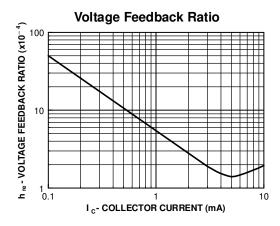


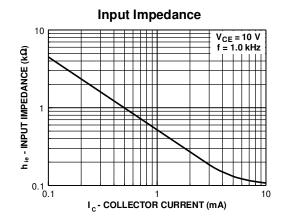


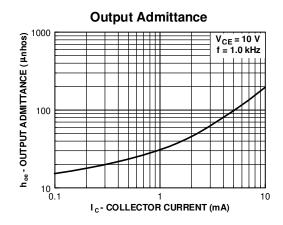
# **PNP General Purpose Amplifier**

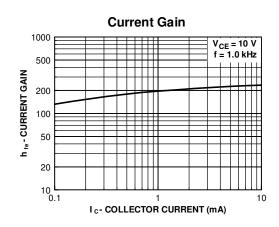
(continued)

# Typical Characteristics (continued)







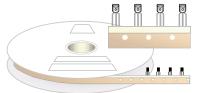


#### **TO-92 Tape and Reel Data** FAIRCHILD SEMICONDUCTOR TM **TO-92 Packaging** Configuration: Figure 1.0 **TAPE and REEL OPTION** FSCINT Label sample See Fig 2.0 for various Reeling Styles CBVR/418019 **FSCINT** Label 5 Reels per Intermediate Box Customized F63TNR Label sample Label F63TNR LOT: CBVK741B019 QTY: 2000 FSID: PN222N Customized QTY1: QTY2: 375mm x 267mm x 375mm Intermediate Box TO-92 TNR/AMMO PACKING INFROMATION **AMMO PACK OPTION** See Fig 3.0 for 2 Ammo Packing Style Quantity EOL code **Pack Options** 2,000 D26Z 2,000 Е D27Z Ammo М 2,000 D74Z D75Z 2,000 **FSCINT** $\begin{array}{ll} \mbox{Unit weight} & = 0.22 \mbox{ gm} \\ \mbox{Reel weight with components} & = 1.04 \mbox{ kg} \\ \mbox{Ammo weight with components} & = 1.02 \mbox{ kg} \\ \mbox{Max quantity per intermediate box} & = 10,000 \mbox{ units} \end{array}$ Label 5 Ammo boxes per Intermediate Box 327mm x 158mm x 135mm Immediate Box Customized F63TNR Customized Label Label 333mm x 231mm x 183mm Intermediate Box (TO-92) BULK PACKING INFORMATION **BULK OPTION** See Bulk Packing DESCRIPTION QUANTITY Information table J18Z TO-18 OPTION STD Anti-static Bubble Sheets TO-5 OPTION STD NO LEAD CLIP 1.5 K / BOX J05Z **FSCINT Label** TO-92 STANDARD STRAIGHT FOR: PKG 92, 94 (NON PROELECTRON NO EOL NO LEADCLIP 2.0 K / BOX SERIES), 96 TO-92 STANDARD STRAIGHT FOR: PKG 94 (PROELECTRON SERIES BCXXX, BFXXX, BSRXXX), 97, 98 L34Z NO LEADCLIP 2.0 K / BOX 2000 units per 114mm x 102mm x 51mm EO70 box for std option Immediate Box 5 EO70 boxes per intermediate Box 530mm x 130mm x 83mm Customized Intermediate box Label FSCINT Label 10,000 units maximum per intermediate box for std option

# TO-92 Tape and Reel Data, continued

#### **TO-92 Reeling Style** Configuration: Figure 2.0

#### Machine Option "A" (H)

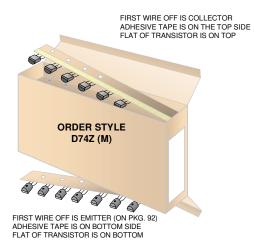


Style "A", D26Z, D70Z (s/h)

# Machine Option "E" (J)

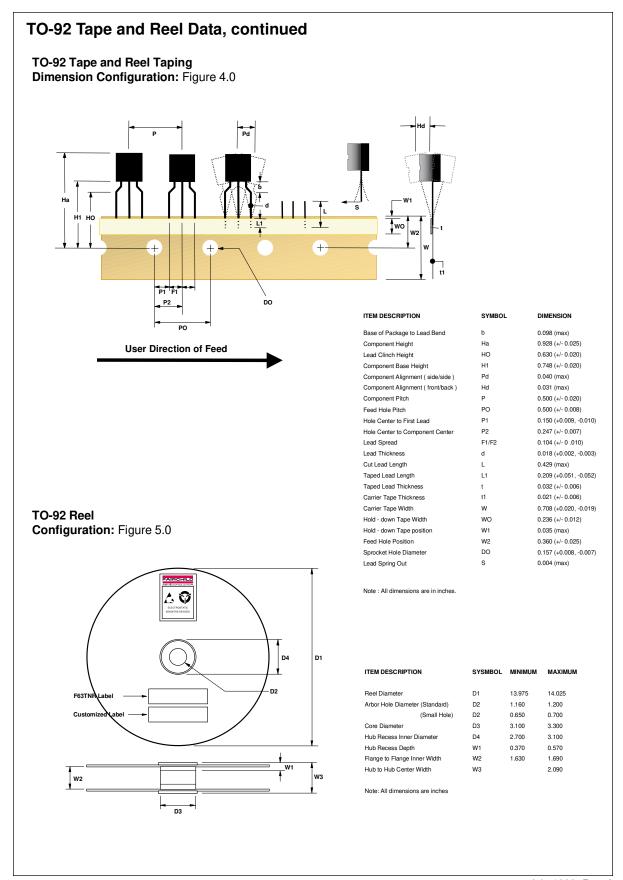
Style "E", D27Z, D71Z (s/h)

#### **TO-92 Radial Ammo Packaging** Configuration: Figure 3.0





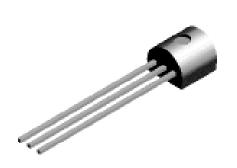
FIRST WIRE OFF IS COLLECTOR (ON PKG. 92) ADHESIVE TAPE IS ON BOTTOM SIDE FLAT OF TRANSISTOR IS ON TOP

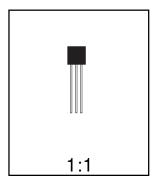


# **TO-92 Package Dimensions**



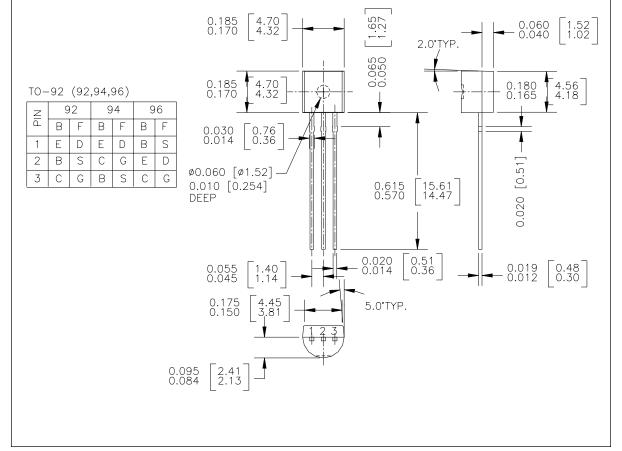
# TO-92 (FS PKG Code 92, 94, 96)

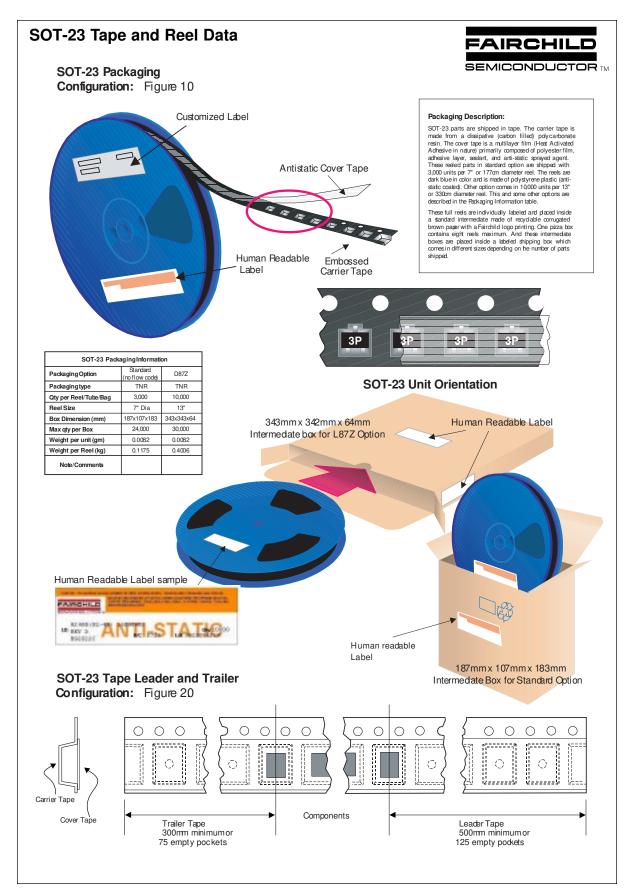




Scale 1:1 on letter size paper
Dimensions shown below are in:
inches [millimeters]

Part Weight per unit (gram): 0.1977

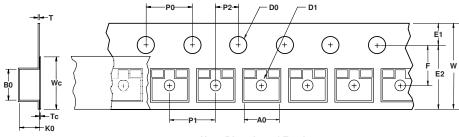




# SOT-23 Tape and Reel Data, continued

### **SOT-23 Embossed Carrier Tape**

Configuration: Figure 3.0



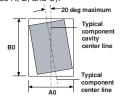
User Direction of Feed

	Dimensions are in millimeter													
Pkg type	Α0	В0	w	D0	D1	E1	E2	F	P1	P0	K0	Т	Wc	Тс
<b>SOT-23</b> (8mm)	3.15 +/-0.10	2.77 +/-0.10	8.0 +/-0.3	1.55 +/-0.05	1.125 +/-0.125	1.75 +/-0.10	6.25 min	3.50 +/-0.05	4.0 +/-0.1	4.0 +/-0.1	1.30 +/-0.10	0.228 +/-0.013	5.2 +/-0.3	0.06 +/-0.02

Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



Sketch A (Side or Front Sectional View)
Component Rotation

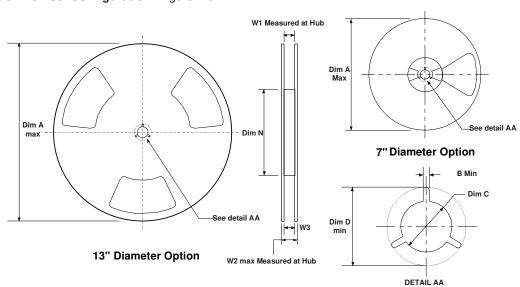


Sketch B (Top View)
Component Rotation



Sketch C (Top View)
Component lateral movement

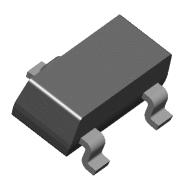
#### SOT-23 Reel Configuration: Figure 4.0

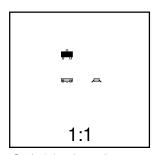


	Dimensions are in inches and millimeters								
Tape Size	Reel Option	Dim A	Dim B	Dim C	Dim D	Dim N	Dim W1	Dim W2	Dim W3 (LSL-USL)
8mm	7" Dia	7.00 177.8	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	2.165 55	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 - 0.429 7.9 - 10.9
8mm	13" Dia	13.00 330	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	4.00 100	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 - 0.429 7.9 - 10.9



# SOT-23 (FS PKG Code 49)

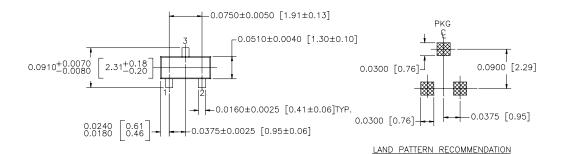


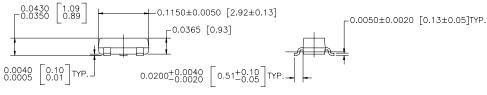


Scale 1:1 on letter size paper

Dimensions shown below are in: inches [millimeters]

Part Weight per unit (gram): 0.0082





CONTROLLING DIMENSION IS INCH VALUES IN [ ] ARE MILLIMETERS SOT 23, 3 LEADS LOW PROFILE

NOTE : UNLESS OTHERWISE SPECIFIED

- 1. STANDARD LEAD FINISH 150 MICROINCHES / 3.81 MICROMETERS MINIMUM TIN / LEAD (SOLDER) ON ALLOY 42
- 2. REFERENCE JEDEC REGISTRATION TO-236, VARIATION AB, ISSUE G, DATED JUL 1993

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Datasheet Identification	Product Status	Definition
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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.